



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:	)	Group Art Unit: 2827
	)	
Michael John Watson	)	
	)	
Serial Number 09/954,528	)	
	)	Examiner: Chambliss
Filed: September 17, 2001	)	
	)	
Title: IMPROVED ADHESIVES FOR	)	
SEMICONDUCTOR APPLICA-	)	
TIONS EFFICIENT PROCESSES	)	
FOR PRODUCING SUCH	)	AMENDMENTS TO
DEVICES AND THE DEVICE	)	THE ABSTRACT
PER SE PRODUCED BY THE	)	
EFFICIENT PROCESSES	)	
	)	
Attorney Docket: DC - 4952	)	April 28, 2003

Assistant Commissioner  
For Patents  
Washington DC 20231

Dear Sir:

Please find enclosed a new page setting forth the amended ABSTRACT.

Respectfully submitted,

Robert L. McKellar  
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## ABSTRACT

Die attach adhesives and methods for their use, along with the devices that are obtained by the use of the methods. Using semiconductor chips as an example, the adhesives and the method for using them provides an interface between a chip (die) and the chip support. The method includes creating a space between the chip and the chip support of a given sized opening by using inorganic insulator particles having an average particle size of 1  $\mu\text{m}$  to 1000  $\mu\text{m}$  and a major axis to minor axis ratio of about 1.0 to 1.5.

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